# Junhui Li

List of Publications by Year
in descending order

Source: https://exaly.com/author-pdf/94356/publications.pdf

Version: 2024-02-01

| 97 | 1,944 | 304743 | 276875 |
|---|---|---|---|
| papers | citations | 22 h-index | 41 g-index |

| 98 | 98 | 98 | 1629 |
|---|---|---|---|
| all docs | docs citations | times ranked | citing authors |

| # | Article | IF | Citations |
|---|---|---|---|
| 1 | Novel Functionalized BN Nanosheets/Epoxy Composites with Advanced Thermal Conductivity and Mechanical Properties. ACS Applied Materials & Interfaces, 2020, 12, 6503-6515. | 8.0 | 314 |
| 2 | Metalâ€“Organic Framework Hexagonal Nanoplates: Bottom-up Synthesis, Topotactic Transformation, and Efficient Oxygen Evolution Reaction. Journal of the American Chemical Society, 2020, 142, 7317-7321. | 13.7 | 140 |
| 3 | Study on a cooling system based on thermoelectric cooler for thermal management of high-power LEDs. Microelectronics Reliability, 2011, 51, 2210-2215. | 1.7 | 123 |
| 4 | New Applications of an Automated System for High-Power LEDs. IEEE/ASME Transactions on Mechatronics, 2016, 21, 1035-1042. | 5.8 | 93 |
| 5 | Interfacial Microstructures and Thermodynamics of Thermosonic Cu-Wire Bonding. IEEE Electron Device Letters, 2011, 32, 1433-1435. | 3.9 | 78 |
| 6 | A molecular dynamics study on thermal and rheological properties of BNNS-epoxy nanocomposites. International Journal of Heat and Mass Transfer, 2018, 126, 353-362. | 4.8 | 58 |
| 7 | A Novel High-Speed Jet Dispenser Driven by Double Piezoelectric Stacks. IEEE Transactions on Industrial Electronics, 2017, 64, 412-419. | 7.9 | 52 |
| 8 | An effective and efficient numerical method for thermal management in 3D stacked integrated circuits. Applied Thermal Engineering, 2017, 121, 200-209. | 6.0 | 49 |
| 9 | Structural Design and Control of a Small-MRF Damper Under 50 N Soft-Landing Applications. IEEE Transactions on Industrial Informatics, 2015, 11, 612-619. | 11.3 | 47 |
| 10 | The soft-landing features of a micro-magnetorheological fluid damper. Applied Physics Letters, 2015, 106, . | 3.3 | 44 |
| 11 | Hollow spherical rare-earth-doped yttrium oxysulfate: A novel structure for upconversion. Nano Research, 2014, 7, 1093-1102. | 10.4 | 42 |
| 12 | Enhanced electric-field-induced strains in (K,Na)NbO3 piezoelectrics from heterogeneous structures. Materials Today, 2021, 46, 44-53. | 14.2 | 36 |
| 13 | Effects of dimension parameters and defect on TSV thermal behavior for 3D IC packaging. Microelectronics Reliability, 2017, 70, 97-102. | 1.7 | 35 |
| 14 | Size-dependent optical-electrical characteristics of blue GaN/InGaN micro-light-emitting diodes. Applied Optics, 2020, 59, 9225. | 1.8 | 35 |
| 15 | Interfacial Characteristics and Dynamic Process of Au- and Cu-Wire Bonding and Overhang Bonding in Microelectronics Packaging. Journal of Microelectromechanical Systems, 2013, 22, 560-568. | 2.5 | 34 |
| 16 | Theoretical and experimental analyses of atom diffusion characteristics on wire bonding interfaces. Journal Physics D: Applied Physics, 2008, 41, 135303. | 2.8 | 33 |
| 17 | Two-dimensional NiSe2 nanosheets on carbon fiber cloth for high-performance lithium-ion batteries. Journal of Alloys and Compounds, 2020, 821, 153218. | 5.5 | 30 |
| 18 | Thermal boundary resistance measurement and analysis across SiC/SiO2 interface. Applied Physics Letters, 2019, 115, . | 3.3 | 28 |

| # | Article | IF | Citations |
|---|---|---|---|
| 19 | Control and Jetting Characteristics of an Innovative Jet Valve With Zoom Mechanism and Opening Electromagnetic Drive. IEEE/ASME Transactions on Mechatronics, 2016, 21, 1185-1188. | 5.8 | 27 |
| 20 | Layered Coâ€“Mn hydroxide nanoflakes grown on carbon cloth as binder-free flexible electrodes for supercapacitors. Journal of Materials Science, 2016, 51, 3784-3792. | 3.7 | 24 |
| 21 | A piezoelectric jetting dispenser with a pin joint. Optik, 2018, 175, 163-171. | 2.9 | 24 |
| 22 | Flow Channel Influence of a Collision-Based Piezoelectric Jetting Dispenser on Jet Performance. Sensors, 2018, 18, 1270. | 3.8 | 23 |
| 23 | Controllable Fabrication and Optical Properties of Uniform Gadolinium Oxysulfate Hollow Spheres. Scientific Reports, 2016, 5, 17934. | 3.3 | 22 |
| 24 | The Mathematical Model and Novel Final Test System for Wafer-Level Packaging. IEEE Transactions on Industrial Informatics, 2017, 13, 1817-1824. | 11.3 | 21 |
| 25 | Improved thermal characteristics of a novel magnetostrictive jet dispenser using water-cooling approach. Applied Thermal Engineering, 2017, 112, 1-6. | 6.0 | 21 |
| 26 | Direct-Acting Piezoelectric Jet Dispenser With Rhombic Mechanical Amplifier. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 910-913. | 2.5 | 21 |
| 27 | New underfill material based on copper nanoparticles coated with silica for high thermally conductive and electrically insulating epoxy composites. Journal of Materials Science, 2019, 54, 6258-6271. | 3.7 | 21 |
| 28 | Nanohole array structured GaN-based white LEDs with improved modulation bandwidth via plasmon resonance and non-radiative energy transfer. Photonics Research, 2021, 9, 1213. | 7.0 | 21 |
| 29 | An Electromechanical Model and Simulation for Test Process of the Wafer Probe. IEEE Transactions on Industrial Electronics, 2017, 64, 1284-1291. | 7.9 | 20 |
| 30 | Enhanced thermal conduction of hybrid filler/polydimethylsiloxane composites via a continuous spatial confining process. Composites Science and Technology, 2022, 226, 109536. | 7.8 | 20 |
| 31 | A Simplified Analysis Method for the Piezo Jet Dispenser with a Diamond Amplifier. Sensors, 2018, 18, 2115. | 3.8 | 19 |
| 32 | Study on Dipping Mathematical Models for the Solder Flip-Chip Bonding in Microelectronics Packaging. IEEE Transactions on Industrial Informatics, 2018, 14, 4746-4754. | 11.3 | 18 |
| 33 | Growth and morphology tuning of ordered nickel nanocones routed by one-step pulse electrodeposition. Applied Surface Science, 2020, 508, 145291. | 6.1 | 18 |
| 34 | Phosphor-free single chip GaN-based white light emitting diodes with a moderate color rendering index and significantly enhanced communications bandwidth. Photonics Research, 2020, 8, 1110. | 7.0 | 17 |
| 35 | Thermal behaviors of nanoparticle reinforced epoxy resins for microelectronics packaging. Microelectronics Reliability, 2019, 93, 39-44. | 1.7 | 16 |
| 36 | High-performance ultra-low-k fluorine-doped nanoporous organosilica films for inter-layer dielectric. Journal of Materials Science, 2019, 54, 2379-2391. | 3.7 | 16 |

| # | Article | IF | Citations |
|---|---|---|---|
| 37 | Composition Tuning of Ultrafine Cobalt-Based Spinel Nanoparticles for Efficient Oxygen Evolution. ACS Sustainable Chemistry and Engineering, 2020, 8, 5534-5543. | 6.7 | 16 |
| 38 | Dipping Process Characteristics Based on Image Processing of Pictures Captured by High-speed Cameras. Nano-Micro Letters, 2015, 7, 1-11. | 27.0 | 15 |
| 39 | Layered rare-earth hydroxide nanocones with facile host composition modification and anion-exchange feature: topotactic transformation into oxide nanocones for upconversion. Nanoscale, 2017, 9, 8185-8191. | 5.6 | 15 |
| 40 | Binder-Free Co<sub>4</sub>N Nanoarray on Carbon Cloth as Flexible High-Performance Anode for Lithium-Ion Batteries. ACS Applied Energy Materials, 2018, 1, 4432-4439. | 5.1 | 13 |
| 41 | Copper Pulse-Reverse Current Electrodeposition to Fill Blind Vias for 3-D TSV Integration. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 1899-1904. | 2.5 | 12 |
| 42 | Electromechanical characteristics and numerical simulation of a new smaller magnetorheological fluid damper. Mechanics Research Communications, 2018, 92, 81-86. | 1.8 | 12 |
| 43 | Structure design and optimization of SOI high-temperature pressure sensor chip. Microelectronics Journal, 2021, 118, 105245. | 2.0 | 12 |
| 44 | Mathematical model of a novel small magnetorheological damper by using outer magnetic field. AIP Advances, 2017, 7, . | 1.3 | 11 |
| 45 | A Multiparameter Numerical Modeling and Simulation of the Dipping Process in Microelectronics Packaging. IEEE Transactions on Industrial Informatics, 2019, 15, 3808-3820. | 11.3 | 11 |
| 46 | Dynamic and Electrical Characteristics of Microprobe Testing in Microelectronics Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 216-222. | 2.5 | 10 |
| 47 | Real-Time Voltage and Resistance Features in Microprobe Testing Process. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 274-278. | 2.5 | 10 |
| 48 | Shortâ€circuit diffusion of ultrasonic bonding interfaces in microelectronic packaging. Surface and Interface Analysis, 2008, 40, 953-957. | 1.8 | 9 |
| 49 | Simultaneously improve the luminous efficiency and color-rendering index of GaN-based white-light-emitting diodes using metal localized surface plasmon resonance. Optics Letters, 2019, 44, 4155. | 3.3 | 9 |
| 50 | Interfacial thermal transport properties and its effect on thermal conductivity of functionalized BNNS/epoxy composites. International Journal of Heat and Mass Transfer, 2022, 195, 123031. | 4.8 | 9 |
| 51 | Mechanisms and Performance Analysis of GaN-Based Micro-LED Grown on Pattern Sapphire Substrate by Laser Lift-Off Process. ECS Journal of Solid State Science and Technology, 2022, 11, 046001. | 1.8 | 8 |
| 52 | Interface features of ultrasonic flip chip bonding and reflow soldering in microelectronic packaging. Surface and Interface Analysis, 2007, 39, 783-786. | 1.8 | 6 |
| 53 | Investigation of the characteristics of overhang bonding for 3-D stacked dies in microelectronics packaging. Microelectronics Reliability, 2011, 51, 2236-2242. | 1.7 | 6 |
| 54 | Study of a dipping method for flip-chip flux coating. Microelectronics Reliability, 2014, 54, 2479-2486. | 1.7 | 6 |

| # | Article | IF | Citations |
|---|---|---|---|
| 55 | Intermetallic Growth Induced Large-Scale Void Growth and Cracking Failure in Line-Type Cu/Solder/Cu Joints Under Current Stressing. Journal of Electronic Materials, 2018, 47, 2499-2506. | 2.2 | 6 |
| 56 | Alternate Restacking of 2â€‰D CoNi Hydroxide and Graphene Oxide Nanosheets for Energetic Oxygen Evolution. ChemSusChem, 2019, 12, 5274-5281. | 6.8 | 6 |
| 57 | Multi-shelled cobaltâ€“nickel oxide/phosphide hollow spheres for an efficient oxygen evolution reaction. Dalton Transactions, 2020, 49, 10918-10927. | 3.3 | 6 |
| 58 | Research on Flip-Chip Bonding Process and Thermal Cycle Reliability Simulation of 3-D Stacked Structure. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2022, 12, 51-58. | 2.5 | 6 |
| 59 | A Measurement Method on Nanoscale Thickness of the Ti Barrier Layer of TSV Structure for 3-D IC. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 954-958. | 2.5 | 5 |
| 60 | A New Automatic Testing System Based on Image Processing and Microprobes for IC-Testing. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 645-652. | 2.5 | 5 |
| 61 | A novel cooling system based on heat pipe with fan for thermal management of high-power LEDs. Journal of Optics (India), 2017, 46, 269-276. | 1.7 | 5 |
| 62 | Thermo-compression bonding process characteristics and shape control of Cu-pillar microbump joints by optimizing of solder melting. Journal of Materials Science: Materials in Electronics, 2022, 33, 10471-10485. | 2.2 | 5 |
| 63 | The analysis of heat pipe cooling in high power LED lighting system. , 2015, , . | | 4 |
| 64 | Investigation on the defect induced thermal mechanical stress for TSV. , 2016, , . | | 4 |
| 65 | Automatic alignment and testing system for wafer with ball grid array. Optik, 2016, 127, 4656-4660. | 2.9 | 4 |
| 66 | Real-Time Electrical Characteristics of Microprobe Testing Process in Microelectronics Packaging. IEEE Transactions on Semiconductor Manufacturing, 2018, 31, 166-172. | 1.7 | 4 |
| 67 | Electromigration in flip chip with Cu pillar having a shallow Sn-3.5Ag solder interconnect. , 2018, , . | | 4 |
| 68 | An Efficient and High Quality Chemical Mechanical Polishing Method for Copper Surface in 3D TSV Integration. IEEE Transactions on Semiconductor Manufacturing, 2019, 32, 346-351. | 1.7 | 4 |
| 69 | Effects of Kovar-4J29 Cylinder Resonance on Ultrasonic Wire Bonding. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 153-160. | 2.5 | 4 |
| 70 | Power and Interface Features of Thermosonic Flip-Chip Bonding. IEEE Transactions on Advanced Packaging, 2008, 31, 442-446. | 1.6 | 3 |
| 71 | High-Frequency and Low-Temperature Thermosonic Bonding of Lead-Free Microsolder Ball on Silver Pad Without Flux. Journal of Electronic Packaging, Transactions of the ASME, 2014, 136, . | 1.8 | 3 |
| 72 | Design and Fabrication of Leadless Package Structure for Pressure Sensors. Journal of Electronic Packaging, Transactions of the ASME, 2022, 144, . | 1.8 | 3 |

| # | Article | IF | Citations |
|---|---|---|---|
| 73 | Atom diffusion mechanism of thermo-sonic flip chip bonding interface. , 2007, , . | | 2 |
| 74 | Improved Image Processing Algorithms for Microprobe Final Test. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, , 1-7. | 2.5 | 2 |
| 75 | Characterization of a Probe Test System With Micro-Magnetorheological Flexible Loading. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1666-1673. | 2.5 | 2 |
| 76 | Effect of Hexagonal-Boron Nitride/Epoxy and BNNS/Epoxy Composite Materials on the Reliability of Flip Chip. Journal of Electronic Packaging, Transactions of the ASME, 2022, 144, . | 1.8 | 2 |
| 77 | The Sintering Process and Vibration Characteristics for Leadless Package Structure of Pressure Sensors. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2022, 12, 209-216. | 2.5 | 2 |
| 78 | Research on Reliability of Ni/Sn/Cu(Ni) Copper Pillar Bump Under Thermoelectric Loading. Journal of Electronic Packaging, Transactions of the ASME, 2022, 144, . | 1.8 | 2 |
| 79 | System design for anti-interference of smoke in metal liquid level detecting. , 2015, , . | | 1 |
| 80 | Investigation on the effect of multiple parameters towards thermal management in 3D Stacked ICs. , 2016, , . | | 1 |
| 81 | A novel testing system based on microprobe and machine vision for IC testing. Optik, 2016, 127, 3664-3668. | 2.9 | 1 |
| 82 | Speed and depth effect of the dipping process for microelectronics packaging. Optik, 2017, 130, 1285-1294. | 2.9 | 1 |
| 83 | Effect of electromigration and aging on evolution of interfacial intermetallic compounds in Cu-Solder-Cu solder joints. , 2017, , . | | 1 |
| 84 | Investigation on the Joule heat and thermal expansion in flip chip package by electro-thermo-mechanical coupling analysis. , 2018, , . | | 1 |
| 85 | Kapitza resistance for nanoscale crystalline and amorphous silicon carbide. , 2018, , . | | 1 |
| 86 | Temperature prediction approach of piezo stacks used in jet valve. Optik, 2019, 198, 163234. | 2.9 | 1 |
| 87 | Theoretical Analysis of Lattice-Mediated Plasmon Resonance Using Finite-Difference Time-Domain Method. Journal of Nanoscience and Nanotechnology, 2019, 19, 40-46. | 0.9 | 1 |
| 88 | Full-color micro-LED displays with cadmium-free quantum dots patterned by photolithography technology: retraction. Applied Optics, 2021, 60, 2281. | 1.8 | 1 |
| 89 | High-G Shock Reliability of 3-D Integrated Structure Microsystem Based on Finite Element Simulation. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 1243-1249. | 2.5 | 1 |
| 90 | Effect of bonding parameters on thermosonic flip chip bonding under pressure constraint pattern. , 2006, , . | | 0 |

| # | Article | IF | Citations |
|---|---|---|---|
| 91 | Analysis of the influence of different parameters on dipping. , 2016, , . | | 0 |
| 92 | Study on the law of multiparameter in dipping process. Optik, 2018, 152, 84-91. | 2.9 | 0 |
| 93 | Sintering Of Hybrid Nano Sliver Paste Achieve Cone-Structured Cu Bonding in die attachment. , 2018, , . | | 0 |
| 94 | SiO2-coated Cu nanoparticle/epoxy resin composite and its application in the chip packaging field. High Performance Polymers, 2019, 31, 417-424. | 1.8 | 0 |
| 95 | Electromechanical Performance of Microprobe Test With Cuboid Magnetorheological Damper in Microelectronic Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2022, 12, 723-730. | 2.5 | 0 |
| 96 | Research on the Mechanical Properties of Magnetorheological Damping and the Performance of Microprobe Test Process. Journal of Electronic Testing: Theory and Applications (JETTA), 0, , 1. | 1.2 | 0 |
| 97 | Opticalâ€“electrical characteristic of green based on GaN micro-LED arrays. Applied Optics, 2022, 61, 5666. | 1.8 | 0 |